



Atty. Dkt. No. 047711-0319

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rajiv SHAH et al.

Title: HIGH RELIABILITY
MULTILAYER CIRCUIT
SUBSTRATES AND METHODS
FOR THEIR FORMATION

Appl. No.: 10/671,996

Filing Date: 9/26/2003

Examiner: Long Pham

Art Unit: 2814

<p>CERTIFICATE OF MAILING</p> <p>I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date below.</p> <p><u>Jose Ramos</u> (Printed Name)</p> <p><u>[Signature]</u> (Signature)</p> <p><u>December 22, 2004</u> (Date of Deposit)</p>
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RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This communication is responsive to the Office Action (Restriction Requirement) dated November 24, 2004, concerning the above-referenced patent application.

Please amend the application as follows:

12/30/2004 SZEWDIE1 00000001 500872 10671996

01 FC:1202 600.00 DA